



MTS-3181US

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: E. Igaki, et al. : Art Unit:  
Serial No.: 09/471,981 : Examiner:  
Filed: December 23, 1999 :  
FOR: INK-JET RECORDING HEAD :

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT  
Assistant Commissioner for Patents  
Washington, D.C. 20231

S I R :

Pursuant to 37 C.F.R. §§ 1.97 and 1.98 and to the duty of disclosure set forth in 37 C.F.R. § 1.56, the Examiner in charge of the above-identified application is requested to consider and make of record the references listed on the PTO 1449 (R&P) submitted herewith. A copy of each of the listed references is also enclosed.

Although the information submitted herewith may be "material" to the Examiner's consideration of the subject application, this submission is not intended to constitute an admission that such information is "prior art" as to the claimed invention.

In accordance with 37 C.F.R. § 1.97(g), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made.

Japanese Reference JP Laid-open No. 2-3311, is not in the English language, but a partial English translation thereof is attached to the copy of the reference submitted herewith.

No first Official Action has yet been received and it is presumed that none has yet been mailed. No fee or certification is required. 37 C.F.R. § 1.97(b).

Respectfully submitted,



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Allan Ratner, Reg. No. 19,717  
Attorney for Applicants

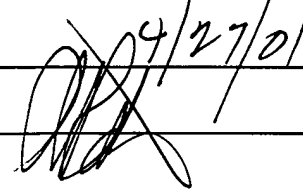
Encls.: PTO Form 1449,  
Copy of (2) References

Dated: April 27, 2001

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The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. 18-0350 of any fees associated with this communication.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on:

  
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